

## Projet 3 - GRADATOR / Gradateur à TRIAC

Projet : EXTRA1  
 Info : [DATA216]  
 Révision : novembre 2000

Figure 3.1. Vue du circuit imprimé (images-composants\xx.jpg).

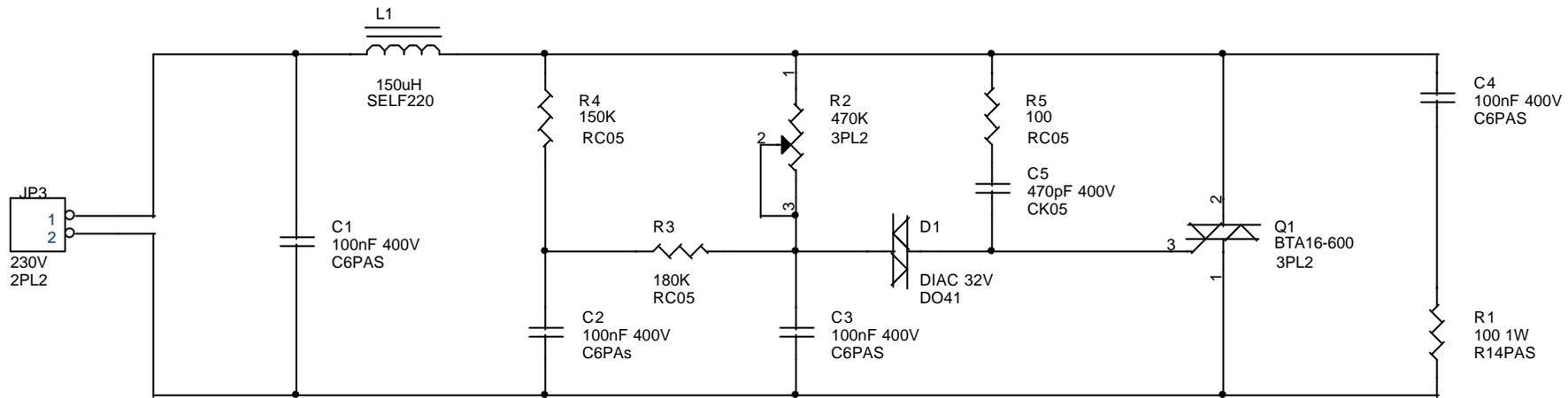
### 3.1 Liste des documents

- Allure des principaux composants.
- Prix du montage.
- Schéma ORCAD ver 9.x.
- Circuit imprimé LAYOUT.
- Documentation du HEF4049B.

### 3.2 Liste des composants

Tableau 3.3. Liste de composants (Projets-EXTRA1.xls / GRADATOR).

No	Quantité	Référence	Désignation	Empreinte
1	4	C1,C2,C3,C4	100nF 400V	C6PAS
2	1	C5	470pF 400V	C6PAS
3	1	D1	DIAC 32V	DO41
4	1	JP3	230V	2PL2
5	1	L1	150uH	SELF220
6	1	Q1	BTA16-600	3PL2
7	1	R1	100 1W	R14PAS
8	1	R2	470K	3PL2
9	1	R3	180K	RC05
10	1	R4	150K	RC05
11	1	R5	100	RC05



Auteur : Thierry LEQUEU

Size  
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Document Number

Gradateur 220 V / 500W

Rev  
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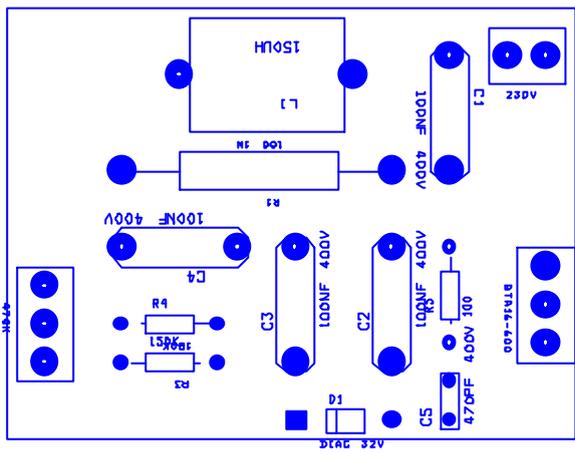
Date: Wednesday, November 22, 2000

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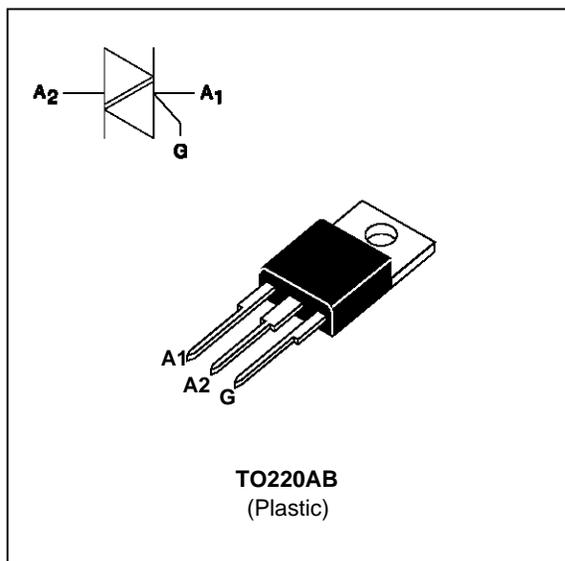
## SNUBBERLESS TRIACS

### FEATURES

- HIGH COMMUTATION :  $(di/dt)_c > 12A/ms$  without snubber
- HIGH SURGE CURRENT :  $I_{TSM} = 120A$
- $V_{DRM}$  UP TO 800V
- BTA Family :  
INSULATING VOLTAGE = 2500V<sub>(RMS)</sub>  
(UL RECOGNIZED : E81734)

### DESCRIPTION

The BTA/BTB12 BW/CW triac family are high performance glass passivated chips technology. The SNUBBERLESS™ concept offer suppression of RC network and it is suitable for application such as phase control and static switching on inductive or resistive load.



### ABSOLUTE RATINGS (limiting values)

Symbol	Parameter		Value	Unit	
I <sub>T(RMS)</sub>	RMS on-state current (360° conduction angle)	BTA	T <sub>c</sub> = 85 °C	12	A
		BTB	T <sub>c</sub> = 95 °C		
I <sub>TSM</sub>	Non repetitive surge peak on-state current ( T <sub>j</sub> initial = 25°C )		tp = 8.3 ms	126	A
			tp = 10 ms	120	
i <sup>2</sup> t	i <sup>2</sup> t value		tp = 10 ms	72	A <sup>2</sup> s
di/dt	Critical rate of rise of on-state current Gate supply : I <sub>G</sub> = 500mA di <sub>G</sub> /dt = 1A/μs		Repetitive F = 50 Hz	20	A/μs
			Non Repetitive	100	
T <sub>stg</sub> T <sub>j</sub>	Storage and operating junction temperature range		- 40 to + 150 - 40 to + 125	°C °C	
TI	Maximum lead temperature for soldering during 10 s at 4.5 mm from case		260	°C	

Symbol	Parameter	BTA / BTB12-... BW/CW				Unit
		400	600	700	800	
V <sub>DRM</sub> V <sub>RRM</sub>	Repetitive peak off-state voltage T <sub>j</sub> = 125 °C	400	600	700	800	V

## BTA12 BW/CW / BTB12 BW/CW

### THERMAL RESISTANCES

Symbol	Parameter		Value	Unit
Rth (j-a)	Junction to ambient		60	°C/W
Rth (j-c) DC	Junction to case for DC	BTA	3.3	°C/W
		BTB	2.7	
Rth (j-c) AC	Junction to case for 360° conduction angle ( F= 50 Hz)	BTA	2.5	°C/W
		BTB	2.0	

### GATE CHARACTERISTICS (maximum values)

$P_G (AV) = 1W$     $P_{GM} = 10W$  (tp = 20 μs)    $I_{GM} = 4A$  (tp = 20 μs)    $V_{GM} = 16V$  (tp = 20 μs).

### ELECTRICAL CHARACTERISTICS

Symbol	Test Conditions	Quadrant		Suffix		Unit	
				BW	CW		
I <sub>GT</sub>	V <sub>D</sub> =12V (DC) R <sub>L</sub> =33Ω	T <sub>j</sub> =25°C	I-II-III	MIN	2	1	mA
				MAX	50	35	
V <sub>GT</sub>	V <sub>D</sub> =12V (DC) R <sub>L</sub> =33Ω	T <sub>j</sub> =25°C	I-II-III	MAX	1.5		V
V <sub>GD</sub>	V <sub>D</sub> =V <sub>DRM</sub> R <sub>L</sub> =3.3kΩ	T <sub>j</sub> =125°C	I-II-III	MIN	0.2		V
t <sub>gt</sub>	V <sub>D</sub> =V <sub>DRM</sub> I <sub>G</sub> = 500mA dI <sub>G</sub> /dt = 3A/μs	T <sub>j</sub> =25°C	I-II-III	TYP	2		μs
I <sub>L</sub>	I <sub>G</sub> =1.2 I <sub>GT</sub>	T <sub>j</sub> =25°C	I-III	TYP	40	-	mA
			II	TYP	80	-	
			I-III	MAX	-	50	
			II	MAX	-	80	
I <sub>H</sub> *	I <sub>T</sub> = 500mA gate open	T <sub>j</sub> =25°C		MAX	50	35	mA
V <sub>TM</sub> *	I <sub>TM</sub> = 17A tp= 380μs	T <sub>j</sub> =25°C		MAX	1.60		V
I <sub>DRM</sub> I <sub>R</sub> RRM	V <sub>DRM</sub> Rated V <sub>R</sub> RRM Rated	T <sub>j</sub> =25°C		MAX	0.01		mA
		T <sub>j</sub> =125°C		MAX	2		
dV/dt *	Linear slope up to V <sub>D</sub> =67%V <sub>DRM</sub> gate open	T <sub>j</sub> =125°C		MIN	500	250	V/μs
				TYP	750	500	
(di/dt) <sub>c</sub> *	Without snubber	T <sub>j</sub> =125°C		MIN	12	6.5	A/ms
				TYP	24	13	

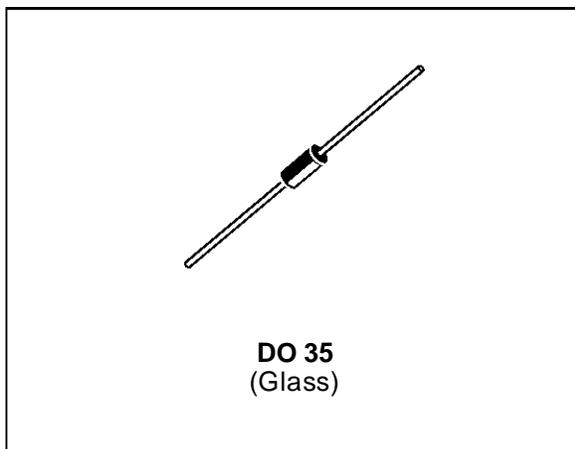
\* For either polarity of electrode A2 voltage with reference to electrode A1.

**TRIGGER DIODES**
**FEATURES**

- $V_{BO}$  : 32V / 34V / 40V VERSIONS
- LOW BREAKOVER CURRENT

**DESCRIPTION**

High reliability glass passivation insuring parameter stability and protection against junction contamination.


**ABSOLUTE RATINGS** (limiting values)

Symbol	Parameter		Value	Unit
P	Power dissipation on printed circuit (L = 10 mm)	$T_a = 65\text{ }^\circ\text{C}$	150	mW
$I_{TRM}$	Repetitive peak on-state current	$t_p = 20\text{ }\mu\text{s}$ $F = 100\text{ Hz}$	2	A
$T_{stg}$ $T_j$	Storage and operating junction temperature range		- 40 to + 125 - 40 to + 125	$^\circ\text{C}$ $^\circ\text{C}$

**THERMAL RESISTANCES**

Symbol	Parameter	Value	Unit
$R_{th(j-a)}$	Junction to ambient	400	$^\circ\text{C/W}$
$R_{th(j-l)}$	Junction-leads	150	$^\circ\text{C/W}$

**DB3 / DB4 / DC34**

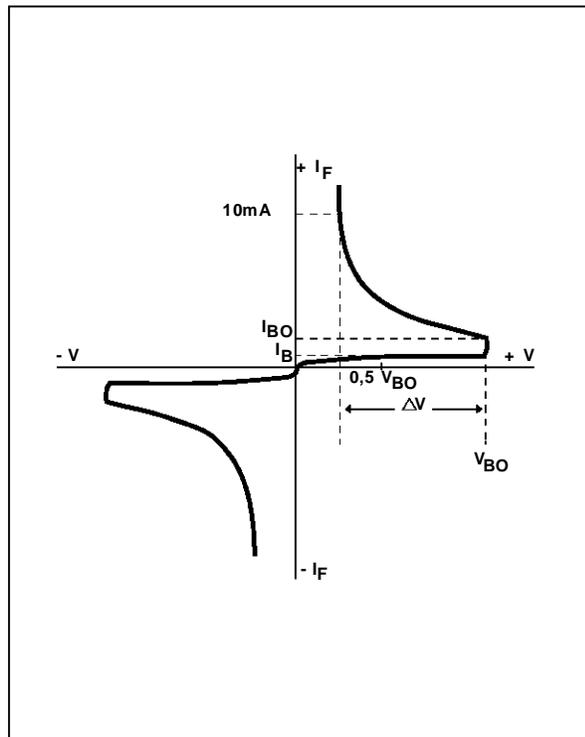
**ELECTRICAL CHARACTERISTICS** (Tj = 25°C)

Symbol	Parameter	Test Conditions		Value			Unit
				DB3	DC34	DB4	
V <sub>BO</sub>	Breakover voltage *	C = 22nF ** see diagram 1	MIN	28	30	35	V
			TYP	32	34	40	
			MAX	36	38	45	
[ +V <sub>BO</sub>   -   -V <sub>BO</sub>  ]	Breakover voltage symmetry	C = 22nF ** see diagram 1	MAX	± 3			V
ΔV ± I	Dynamic breakover voltage *	ΔI = [I <sub>BO</sub> to I <sub>F</sub> =10mA] see diagram 1	MIN	5			V
V <sub>O</sub>	Output voltage *	see diagram 2	MIN	5			V
I <sub>BO</sub>	Breakover current *	C = 22nF **	MAX	100	50	100	μA
t <sub>r</sub>	Rise time *	see diagram 3	TYP	1.5			μs
I <sub>B</sub>	Leakage current *	V <sub>B</sub> = 0.5 V <sub>BO</sub> max see diagram 1	MAX	10			μA

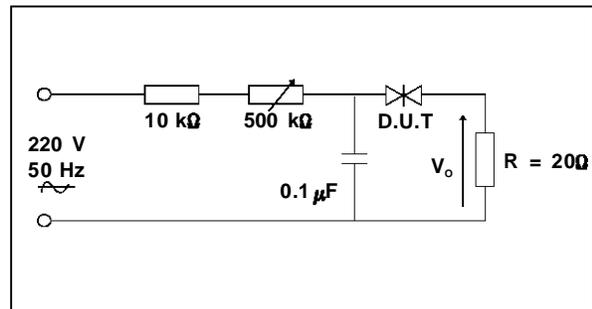
\* Electrical characteristic applicable in both forward and reverse directions.

\*\* Connected in parallel with the devices.

**DIAGRAM 1 : Current-voltage characteristics**



**DIAGRAM 2 : Test circuit for output voltage**



**DIAGRAM 3 : Test circuit see diagram 2.  
Adjust R for I<sub>p</sub>=0.5A**

